

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE



Application for:

Chuan Hu et al.

Application No.: 10/811,370

Filed: 03/25/2004

For: Bumpless Die and Heat Spreader  
Lid Module Bonded to Bumped Die  
Carrier

Examiner: Tu-Tu V. Ho

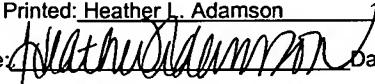
Art Group: 2818

Confirmation No.: 2079

CERTIFICATE OF TRANSMISSION/MAILING

I hereby certify that this correspondence is being facsimile transmitted to the USPTO or deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to: Commissioner for Patents, PO Box 1450, Alexandria, VA 22313-1450 on the date shown

Typed or Printed: Heather L. Adamson

Signature:  Date: 10/19/2005

Mail Stop Amendment  
Commissioner for Patents  
PO Box 1450  
Alexandria, VA 22313-1450

**AMENDMENT AND RESPONSE TO OFFICE ACTION**

Sir:

In response to the Office Action mailed September 01, 2005, Applicants submit the following response:

**Amendments to the Specification – none;**

**Amendments to the Claims – begin on page 2 of this paper;**

**Amendments to the Drawings – none;**

**Remarks/Arguments - begin on page 7 of this paper.**